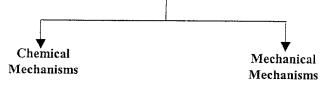
## **Laser Assisted Particle Removal**



- Photochemical reactive removal
- Photo- + thermochemical reactive removal

- Particle deformation
- Substrate deformation
- Energy transfer medium explosive evaporation

Fig. 1

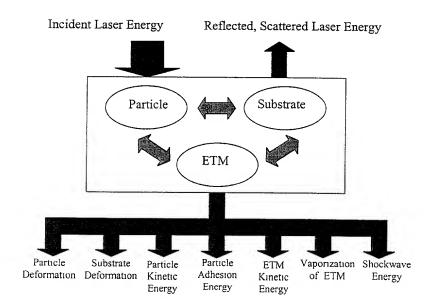


Fig. 2

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Absorption Medium	Particle	ETM	Substrate with ETM	Substrate without ETM
Removal Mechanism	Rapid thermal expansion of particle	Explosive evaporation of ETM	Microbubble formation at liquid/solid interface	Rapid thermal expansion of the substrate
wavelength	λ< <particle diameter<="" td=""><td>λ&gt;&gt;Particle Diameter</td><td>λ&gt;Particle Diameter</td><td>λ&gt;&gt;Particle Diameter or λ<particle diameter="" if="" α<sub="">particle is low</particle></td></particle>	λ>>Particle Diameter	λ>Particle Diameter	λ>>Particle Diameter or λ <particle diameter="" if="" α<sub="">particle is low</particle>
Energy Absorption	$\alpha_{particle} >> \alpha_{substrate}$	High α <sub>ΕΤΜ</sub>	High α <sub>substrate</sub>	High α <sub>suostrate</sub>
Substrate Damage	-Melting/Ablation of particle	Shockwave, substrate absorption	-Melting/Ablation of particle or substrate -Shockwave in ETM	Melting/Ablation of particle or substrate
Particle Removal Threshold	Φ <sub>h</sub> =0.01-0.08 J/cm <sup>2</sup> l <sub>th</sub> =1-11 MW/cm <sup>2</sup> D=20 μm	Φ <sub>th</sub> =0.65-2.2 J/cm <sup>2</sup> I <sub>th</sub> =3-11 MW/cm <sup>2</sup>	$\Phi_{th}$ =0.02-0.3 J/cm <sup>2</sup> $I_{th}$ =2-600 MW/cm <sup>2</sup> $\tau$ =0.03-20 ns	$\Phi_{th}$ =0.02-0.3 J/cm <sup>2</sup> $l_{th}$ =1-30 MW/cm <sup>2</sup> $\tau$ =7-30 ns

Fig. 3

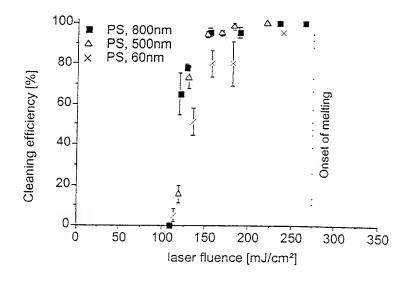


Fig. 4

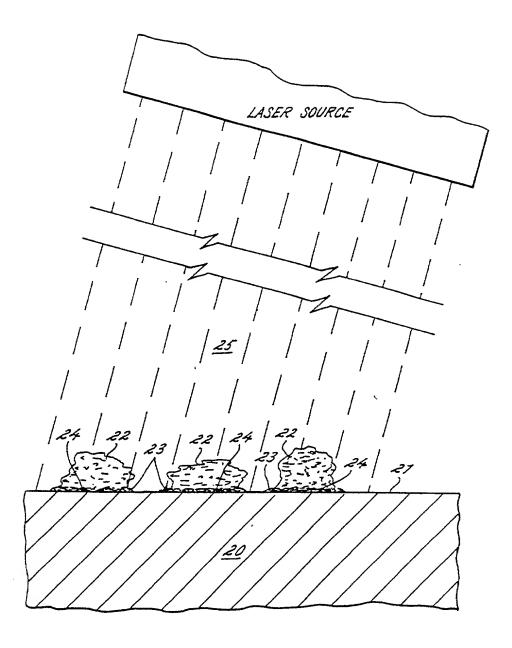
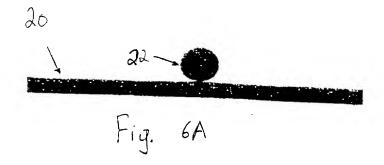
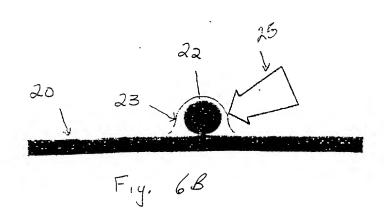
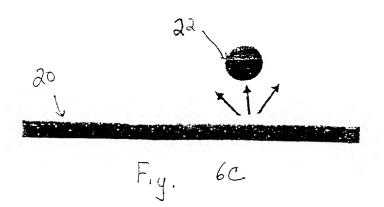


FIG. 5







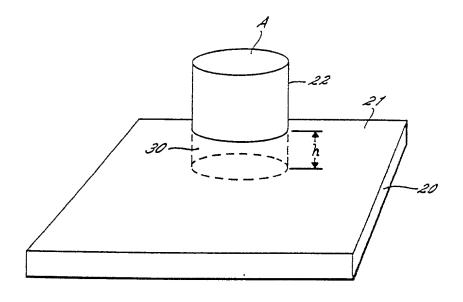
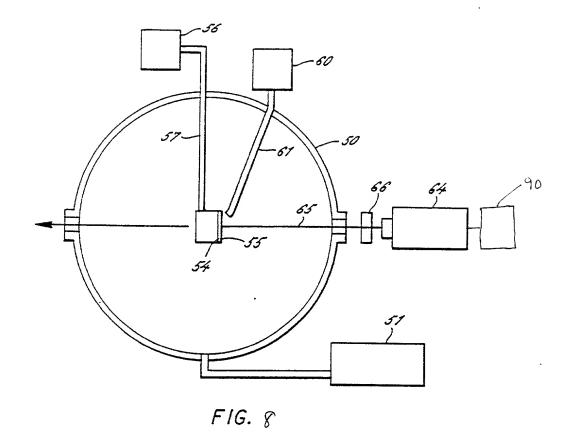


FIG. 7

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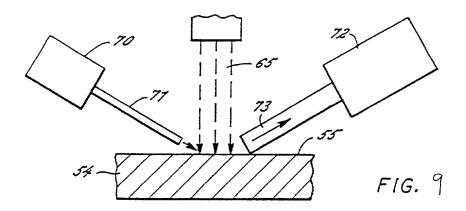
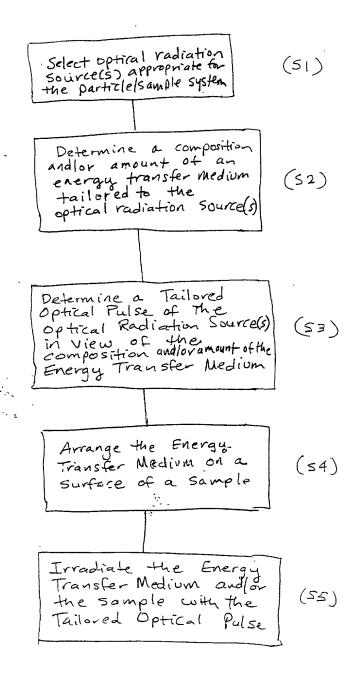


Figure 10



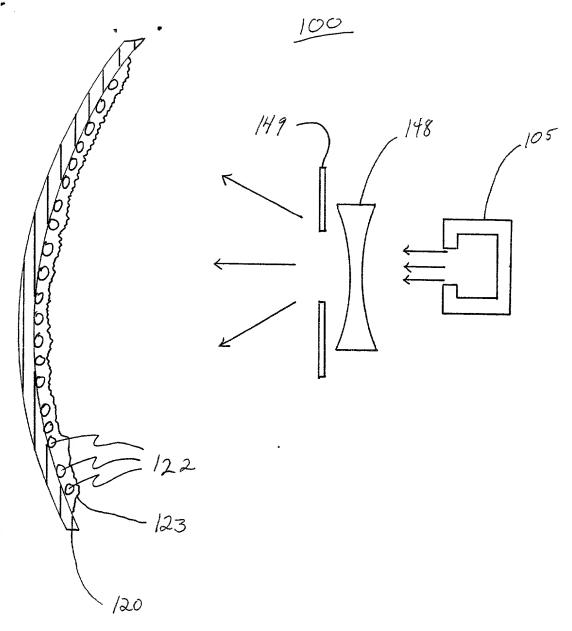


Fig. 11

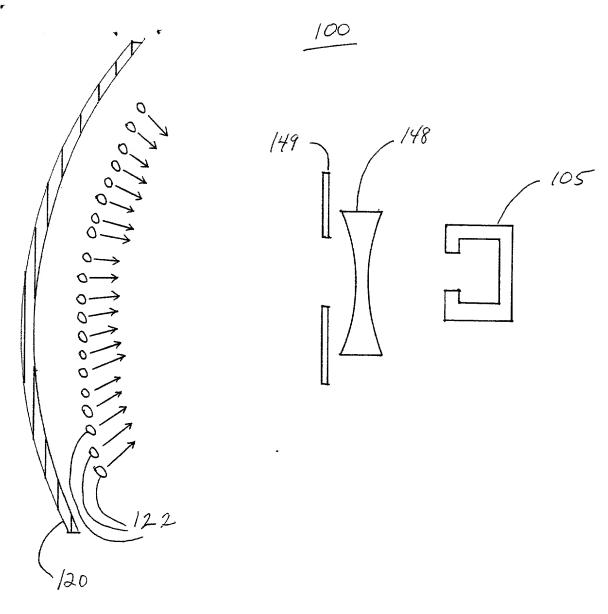


Fig 12

Fig 13